



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT

In re Application of: Hui et al.

Serial No.: 09/916,197

Filed: July 27, 2001

For: METHOD FOR ENCAPSULATING
INTERMEDIATE CONDUCTIVE ELEMENTS
CONNECTING A SEMICONDUCTOR DIE TO A
SUBSTRATE AND SEMICONDUCTOR DEVICES
SO PACKAGED

Confirmation No.: 7070

Examiner: J. Vigushin

Group Art Unit: 2827

Attorney Docket No.: 2269-4712US
(99-1054.00/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

10-7-03
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Deidra J. Pfeil

Name (Type/Print)

AMENDMENT UNDER 37 C.F.R. §1.116

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This Amendment is being filed in response to the Final Office Action mailed on August 7, 2003, the three-month shortened statutory period for response to which expires on November 7, 2003. This response is being submitted within two months of the mailing date of the Final Office Action.

Amendments to the Claims are reflected in the listing of claims, which starts at page 2 of this paper.

Corrections to the Drawings begin on page 21 of this paper and include both an attached replacement sheet and an annotated sheet showing changes.

Remarks begin on page 22 of this paper.